

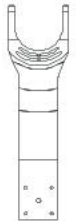
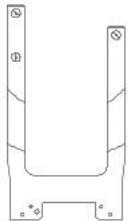
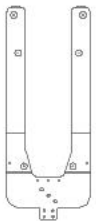
Fortrend Robot Selection Rules

FWRD-Z400-R190.5-Rta-Ata-F-8-MRTX-MOD

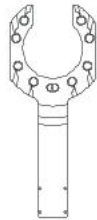
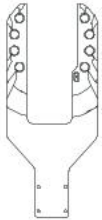
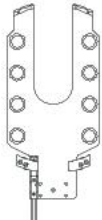
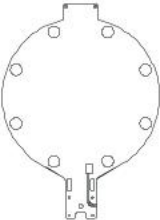
F:Fortrend W:wafer P:PLP substrate M:Mask C:Cassette H:humid	Axis-Z Height 240mm 300mm 400mm 500mm Z*XXX(Customized) LZ: Compact Lifting Height: 240mm 300mm 400mm 500mm LZ*XXX (Customized) Dual-Z ZD600mm ZD700mm ZD800mm ZD*XXX(Customized) Module-based MZXXX	Drive arm R length Special module 146mm 190.5mm 213mm Eccentric ER (optional)	Special module Rta: : Single arm FLIP Rta2: Double Arm Up FLIP Rta2: Double Arm Down FLIP RtaD: Double arm double FLIP FR: wafer frame No Options	Wafer Size 4/6/8/12 N*:Non-wafer object	Special Customization Have: Special Model None: Normal Device
R:Robot				Fork Type F:Original fork No Options	
D:Arm Qty. S:Single arm D:Dual-arm A*:X(X:Number of Arms)				End-effector Type Ata:Vacuum suction Cta:Edge gripper Han:Clamp lift type Ber1:Contact Bernoulli Ber2:Non-Contact Bernoulli Customer Customization	Matching Options M: M1:Opposite-shooting Mapping Quantity 1 M2:Opposite-shooting Mapping Quantity 2 M*:Mapping Quantity 1 No Options R: R:Original teach pendant No Options TX: T:Original Track axis X:TRACK axis effective distance/mm No Options

Robot Fork Series

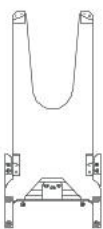
Vacuum Fork

					
Standard Vacuum Suction Y-Type	Standard Vacuum Suction Linear Type	U-shaped Vacuum Fork for Takio Plate	Fork for Large Warping 1.5-5mm	Multi-hole Vacuum Suction Fork	Vacuum Suction & Friction Pad Fork

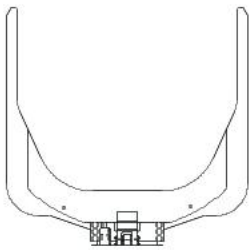
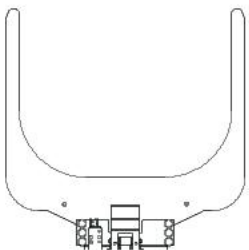
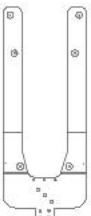
Bernoulli Fork

				
Contact Bernoulli Circular Type	Edge Contact Bernoulli	Contact Bernoulli Y-shaped	Edge Contactless Bernoulli	Edge Clamping Non-contact Bernoulli

Wafer-holding Fork

		
Gripper Type Fork	Gripper Rotating Type	Compatible Fork

Frame-type Fork

		
Frame Gripping Fork	Frame Clamping Fork	Frame Vacuum Suction Fork

Transfer Robot



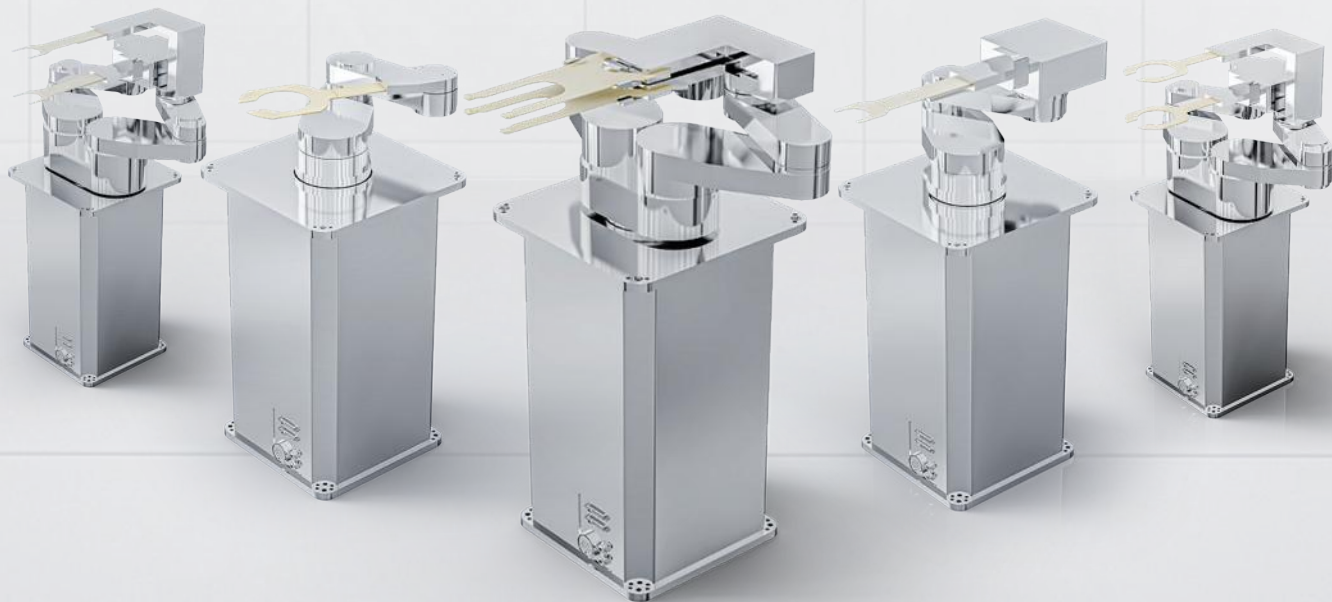
High efficiency



Highly refined



High stability



- The core components are fully developed in-house, and the entire machine is assembled and produced at the Fortrend Wuxi manufacturing base, ensuring greater reliability;
- The device features RS232 serial interface and Ethernet bus communication, making operation more convenient;
- It is equipped with the Smart Move function and features a teaching design, making it more intelligent;
- It offers a variety of end-effector specifications and customizable linear modules to meet the needs of diverse working conditions.

Specification parameter		
Project	Specification	
Structure	3-6 Axis (Servo Motor) Z-axis: Motor with Brake	
Wafer Size	2-inch to 12-inch Wafer	
Working Range	R-axis	146mm/190.5mm/213mm
	Single Z-axis	240mm/300mm/400mm/500mm
	Dual Z-axis	600mm/700mm/800mm/920mm
	θ-axis	340°
	Flip-axis	180°
	Track	Customizable according to working conditions
Maximum Speed	R-axis	1500mm/S
	Single Z-axis	500mm/S
	Dual Z-axis	800mm/S
	θ-axis	235~340°/S
	Flip-axis	360°/S
	Track	800mm—1500mm
Maximum Payload	Third joint center 3Kg or less	
Repeatability	± 0.1mm	
Cleanliness Class	Highest ISO Class 1	
Noise Level	80 dB or lower	
Robot Material	Aluminum alloy	
EEF (End Effector)	Ceramic/carbon fiber/aluminum alloy, etc. (customized as required)	
Operating Voltage	220V	
Communication Method	Ethernet communication/RS232	
Communication Protocol	HEX/ASCII	
Air Supply	Positive pressure: 0.15-0.5Mpa/Negative pressure: -70- -90Kpa	

Application Cases



FWRS-3-Axis Single-Arm Robot Series

This mechanical arm is designed for material handling in high-cleanliness environments, employing a closed-loop servo control system and is suitable for high-speed transportation.



- Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout
- Carrying capacity: Below 3Kg at the third joint of the arm
- Compatible with various types of Forks to meet the wafer transfer needs for different jobs
- Wafer securing methods: Vacuum suction type / Clamping type / Clamping and lifting type / Contact Bernoulli type / Non-contact Bernoulli type
- Based on the equipment layout, you can choose either an upper or lower fixing method

Application: Suitable for various semiconductor equipment, including EFEM, Sorter, inspection equipment, etc.

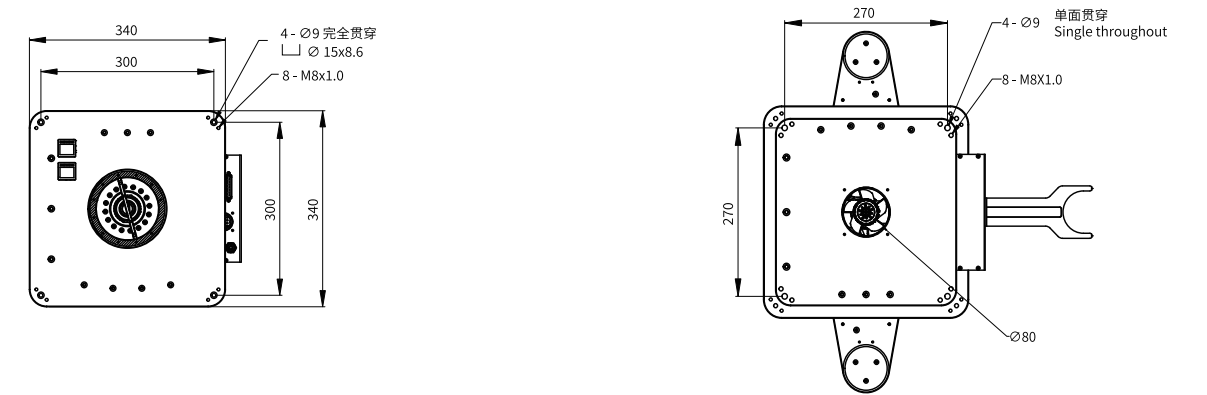
Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Rotation: 340°	Lifting: 240/300/400/500
Handling Speed (average speed)	750mm/S	235~340°/S	500mm/S
Arm Type	Single Arm		
Handling Height	700-1000mm		
Repeatability Accuracy	Within ± 0.1mm		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

RANGE OF MOTION

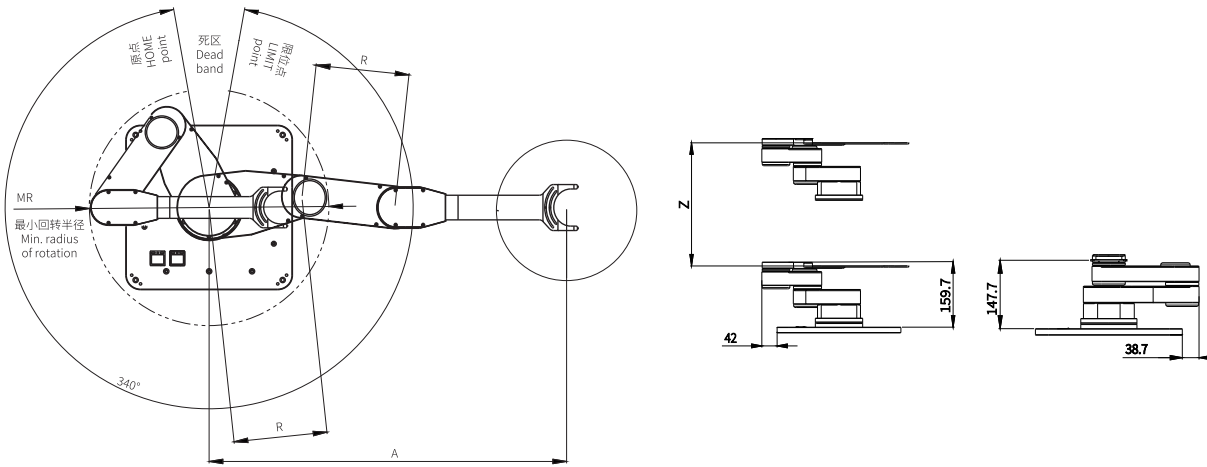
- Top fixed mode

(Fix the counterbore and adjust the screw according to the configuration)
- Bottom fixed mode

(Fix the counterbore and adjust the screw according to the configuration)



Single - arm robot motion range schematic



Model	Z	R	MR*	A*
FWRS	300/400/500	146	8寸540	600
		190.5	12寸610	680

The arm length and minimum rotation radius may vary depending on the specific end effectors and drive shafts selected. The actual length should be based on the final product.

FWRD-Four-Axis Dual-Arm Robot Series

This mechanical arm is designed for material handling in high-cleanliness environments, employing a closed-loop servo control system and is suitable for high-speed transportation.



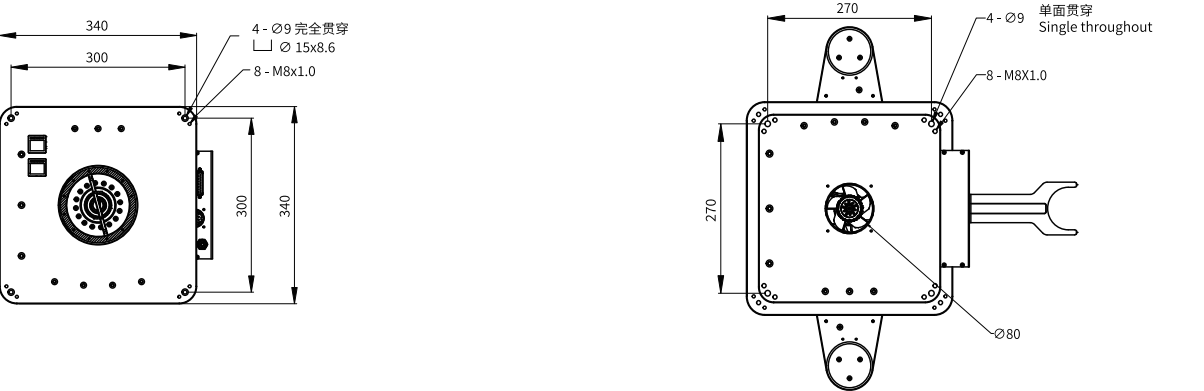
- Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout
- Utilizing a dual-arm structure to achieve high-speed wafer transfer
- Carrying capacity: Below 3Kg at the third joint of the arm
- Compatible with various types of Forks to meet the wafer transfer needs for different jobs
- Wafer securing methods: Vacuum suction type / Clamping type / Clamping and lifting type / Contact Bernoulli type / Non-contact Bernoulli type
- Based on the equipment layout, you can choose either an upper or lower fixing method

Application: Suitable for high-speed wafer handling in atmospheric environments, applicable to various semiconductor equipment, including EFEM (Equipment Front End Module), Sorter, coating and developing equipment, cleaning equipment, and inspection equipment

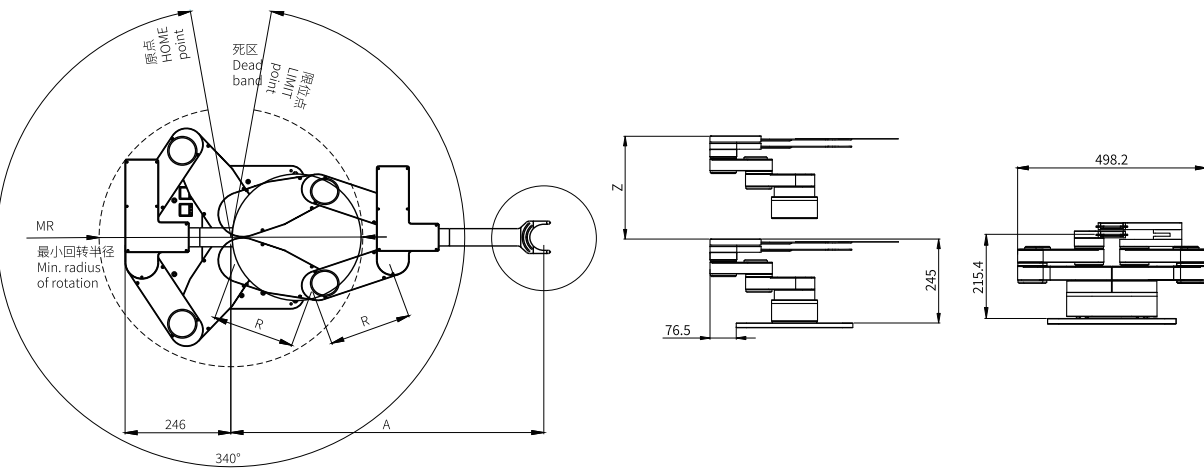
Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Rotation:340度	Lifting:240/300/400/500
Handling Speed (average speed)	750mm/s	235~340°/s	500mm/s
Arm Type	Dual Arms		
Handling Height	700-1020mm		
Repeatability Accuracy	Within ± 0.1mm		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

RANGE OF MOTION

- Top fixed mode
(Fix the counterbore and adjust the screw according to the configuration)
- Bottom fixed mode
(Fix the counterbore and adjust the screw according to the configuration)



Schematic diagram of the motion range for a dual-arm robotic arm



Model	Z	R	MR*	A*
FWRS	300	146	8寸520	600
	400	190.5	8寸600	720
	500	213	12寸630	910

The arm length and minimum rotation radius may vary depending on the specific end effectors and drive shafts selected. The actual length should be based on the final product.

FPRD Series Dual-Arm 4-Axis PLP Robot

This mechanical arm is designed for material handling in high-cleanliness environments. It employs a closed-loop control system and is suitable for the transportation of PLP glass substrates.



Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout

Carrying weight: below 4Kg

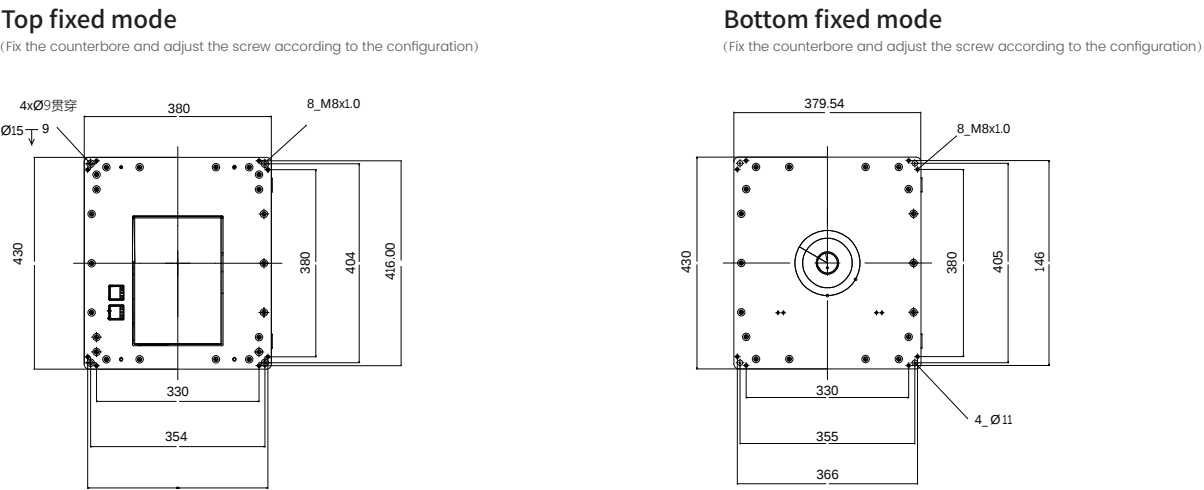
Capable of being paired with different types of Forks to meet various wafer transfer requirements

Fixed methods can be chosen either from the top or bottom based on the equipment layout

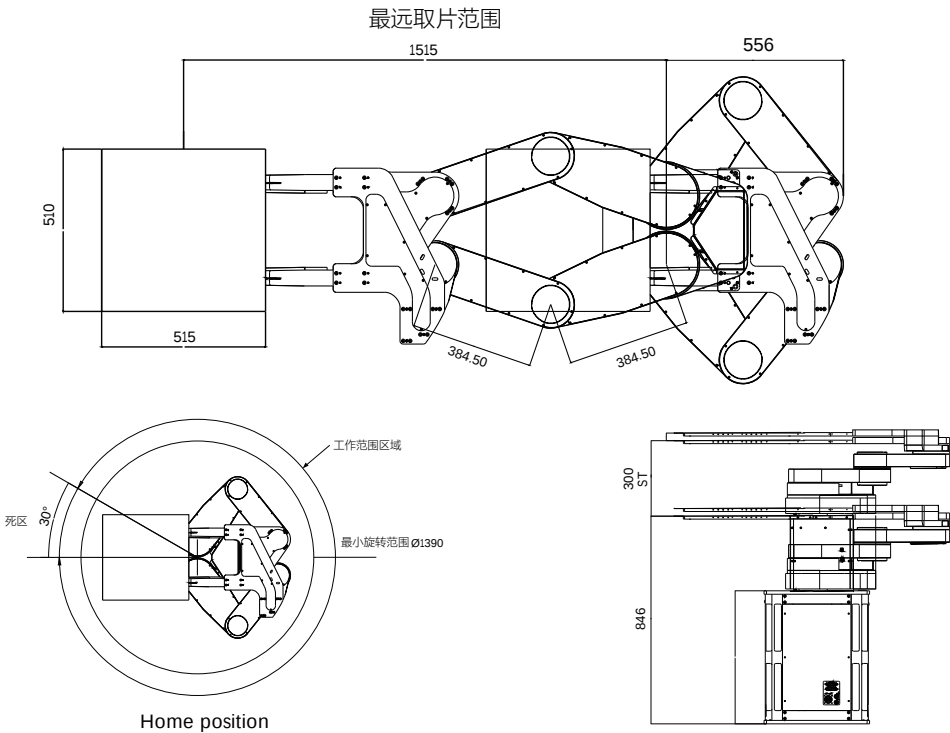
● Application: High-cleanliness, space-constrained glass substrate PLP EFEM and similar equipment.

Specification parameter			
Handling Object	515*510mm Glass Substrate		
Reachable Range	Arm: 376/500/760mm	Theta Rotation:340°	Lifting:Z300/ZD500/ZD700
Handling Speed (average speed)	550mm/s	200°/s	300mm/s
Arm Type	Dual Arms		
Handling Height	890mm		
Repeatability Accuracy	Within ± 0.2mm		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

RANGE OF MOTION



Schematic diagram of the motion range for a dual-arm robotic arm



The arm length and minimum rotation radius may vary depending on the specific end effectors and drive shafts selected. The actual length should be based on the final product.

FWRS Series Single-Arm Rotary Robot with 4-Axis

This mechanical arm is designed for material handling in high-cleanliness environments. It features a closed-loop control system and is suitable for applications where End Effector (EEF) rotation is required.



- Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout
- The EEF can achieve a flip from 0 to 180 degrees
- Carrying capacity: Below 3Kg at the third joint of the arm
- Compatible with various types of Forks to meet the wafer transfer needs for different jobs
- Wafer retention methods: Vacuum suction type/Clamping type/Contact Bernoulli type/Non-contact Bernoulli type
- Based on the equipment layout, you can choose either an upper or lower fixing method

● **Application:** High-speed wafer handling in atmospheric environments, suitable for various semiconductor equipment such as EFEM, Sorter, coating and developing equipment, cleaning equipment, and inspection equipment.

Specification parameter				
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers			
Reachable Range	Arm: 290/376mm	Rotation: 340°	Lifting:240/300/400/500	Flip Rotation:180°
Handling Speed (average speed)	750mm/s	340°/s	500mm/s	360°/s
Arm Type	Single Arm			
Handling Height	690-1050mm			
Repeatability Accuracy	± 0.1mm Within			
Communication Protocol	HEX/ASCII			
Communication Method	EtherNet/RS232			
Cleanliness	Highest ISO Class 1			
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa			

FWRD-Five/Six-Axis Dual-Arm Flip Manipulator Series

This mechanical arm is designed for material handling in high-cleanliness environments. It features a closed-loop control system and is suitable for applications where End Effector (EEF) rotation is required.



- Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout
- Utilizing a dual-arm structure to achieve high-speed wafer transfer
- Utilizing a dual-arm structure to achieve high-speed wafer transfer
- Carrying capacity: Below 3Kg at the third joint of the arm
- Carrying capacity: Below 3Kg at the third joint of the arm
- Wafer holding methods: Vacuum suction/Clamping/Contact Bernoulli/Non-contact Bernoulli
- Carrying capacity: Below 3Kg at the third joint of the arm

● **Application:** High-speed wafer handling in atmospheric conditions, suitable for various semiconductor equipment, including EFEM, Sorter, cleaning equipment, and inspection equipment.

Specification parameter				
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers			
Reachable Range	Arm: 290/376mm	Rotation: 340°	Lifting:240/300/400/500	Flip Rotation:180°
Handling Speed (average speed)	750mm/s	235~340°/s	500mm/s	360°/s
Arm Type	Dual-arm Single Flip/Dual-arm Double Flip Options Available			
Handling Height	690-1050mm			
Repeatability Accuracy	Within ± 0.1mm			
Communication Protocol	HEX/ASCII			
Communication Method	EtherNet/RS232			
Cleanliness	Highest ISO Class 1			
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa			

FMRS-Three-Axis MASK Single-Arm Manipulator

This mechanical arm is designed for material handling in high-cleanliness environments. It employs a closed-loop control system and is suitable for the transfer of MASK wafers and square glass plates.



Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout

The EEF employs a closed-loop control system using a gripping mechanism

Carrying capacity: Below 3Kg at the third joint of the arm

Compatible with various types of Forks to meet the wafer transfer needs for different applications

Wafer holding methods: Clamping type, Lifting type

Based on the equipment layout, you can choose either an upper or lower fixing method

● **Application:** Suitable for working conditions with high requirements for cleanliness, precision, and reliability, ensuring the efficient and stable transfer of photomask (MASK) wafers in lithography processes. It is applicable to MASK EFEM and other MASK wafer transfer systems.

Specification parameter			
Handling Object	Mask Wafer/Square Glass Wafer		
Reachable Range	Arm: 376mm	Theta Rotation: 340°	Lifting:240/300/400/500
Handling Speed (average speed)	600mm/s	235°/s	250mm/s
Arm Type	Single Arm		
Handling Height	520-820mm		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

FMRD-Four-Axis MASK Dual-Arm Manipulator

This mechanical arm is designed for material handling in high-cleanliness environments. It employs a closed-loop control system and is suitable for the transfer of MASK wafers and square glass plates.



Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout;

The EEF employs a closed-loop control system using a gripping mechanism;

Adopting a dual-arm structure, the robotic arm can reduce the wafer exchange time.

Wafer holding methods: Clamping type, Lifting type;

Compatible with various types of Forks to meet the wafer transfer needs for different applications;

Carrying capacity: Below 3Kg at the third joint of the arm;

Based on the equipment layout, you can choose either an upper or lower fixing method.

● **Application:** Suitable for working conditions with high requirements for cleanliness, precision, and reliability, ensuring the efficient and stable transfer of photomask (MASK) wafers in lithography processes. It is applicable to MASK EFEM and other MASK wafer transfer systems.

Specification parameter			
Handling Object	Mask Wafer/Square Glass Wafer		
Reachable Range	Arm: 376mm	Theta Rotation: 340°	Lifting:240/300/400/500
Handling Speed (average speed)	600mm/s	235°/s	250mm/s
Arm Type	Dual Arms		
Handling Height	520-820mm		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

FHRS-Three-Axis Humid Single-Arm Manipulator

This robotic arm is suitable for wafer transfer in waterproof environments and can be used in conjunction with a wafer flipper and edge grip mechanism. It has a protection level of IP64 and is capable of handling wafers in acidic, alkaline, and cleaning environments.



Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout

Carrying capacity: Below 3Kg at the third joint of the arm

The arm section is coated with Teflon to ensure corrosion resistance

O-ring seals are used at component joint interfaces

The waterproof structure of the Z-axis utilizes an accordion-style bellows

Wafer fixing methods: Vacuum suction type / Clamping type

● Application: High-speed transportation of semiconductor wafers in waterproof environments, suitable for various wet process semiconductor equipment, EFEM (Equipment Front End Module), Sorter, and other cleaning process equipment.

Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Theta Rotation: 340°	Lifting:300/400/500
Handling Speed (average speed)	750mm/s	235°/s	500mm/s
Arm Type	Single Arm		
Handling Height	780--980mm		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class1		
Facilities	Power: 220V, 10A, Vacuum: -70--90Kpa, Positive Pressure: 0.1—0.5Mpa		

FHRD-Four-Axis Humid Dual-Arm Manipulator

This manipulator is suitable for wafer transfer in waterproof environments and can be used in conjunction with wafer flipping and edge clamping mechanisms. It has a protection level of IP64, enabling the handling of wafers in acidic, alkaline, and cleaning environments.



Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout

The arm section is coated with Teflon to ensure corrosion resistance

Carrying capacity: Below 3Kg at the third joint of the arm

O-ring seals are used at component joint interfaces

The waterproof structure of the Z-axis utilizes an accordion-style bellows

Wafer fixing methods: Vacuum suction type / Clamping type

Adopting a dual-arm structure, the robotic arm can reduce the wafer exchange time

Based on the equipment layout, you can choose either an upper or lower fixing method

● Application: High-speed transportation of semiconductor wafers in waterproof environments, suitable for various wet process semiconductor equipment, EFEM (Equipment Front End Module), Sorter, and other cleaning process equipment.

Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Theta Rotation: 340°	Lifting:300/400/500
Handling Speed (average speed)	750mm/s	235°/s	500mm/s
Arm Type	Dual Arms		
Handling Height	800--1000mm		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class1		
Facilities	Power: 220V, 10A, Vacuum: -70--90Kpa, Positive Pressure: 0.1—0.5Mpa		

FHRA*4-6 Axis Humid Quadruple-Arm Robot

This robotic arm is suitable for wafer transfer in waterproof environments and can be equipped with vacuum suction/edge clamping mechanisms. It has an IP64 protection rating, allowing it to handle wafers in acidic, alkaline, and cleaning environments.



Equipped with four Forks, it can be separated for dry and wet handling.

Carrying capacity: Below 3Kg at the third joint of the arm

Wafer fixing methods: Vacuum suction type / Clamping type

Using a 4-arm structure, with independent motion for wafer transfer, reduces wafer exchange time

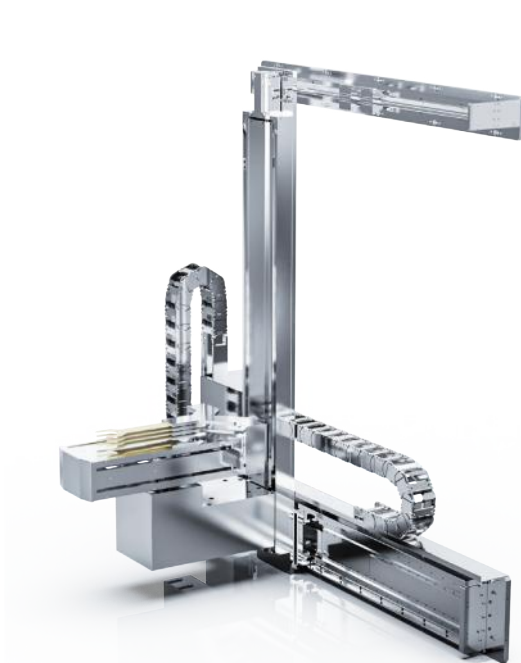
The arm reach and track travel can be customized according to actual working conditions

● Application: High-speed wafer handling in waterproof environments, suitable for various semiconductor equipment related to wet processes, including EFEM, Sorter, and cleaning process equipment with compact space requirements.

Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Theta Rotation: 340°	Lifting:300/400/500
Handling Speed (average speed)	1000mm/s	200°/s	500mm/s
Arm Type	Single Arm		
Handling Height	692--792		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

FHRA*4-7 Axis Humid Quadruple-Arm Robot

This robotic arm is suitable for wafer transfer in waterproof environments and can be equipped with vacuum suction/edge clamping mechanisms. It has an IP64 protection rating, allowing it to handle wafers in acidic, alkaline, and cleaning environments.



Equipped with four Forks, it can be separated for dry and wet handling.

Carrying capacity: Below 500g at the third joint of the arm

Carrying capacity: Below 3Kg at the third joint of the arm

Wafer fixing methods: Vacuum suction type / Clamping type

Using a 4-arm structure, with independent motion for wafer transfer, reduces wafer exchange time

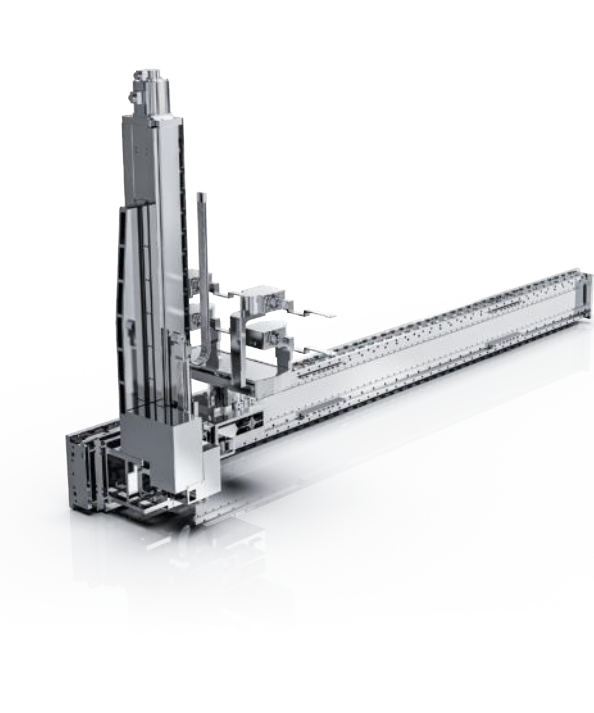
The arm reach and track travel can be customized according to actual working conditions

● Application: High-speed wafer handling in waterproof environments, suitable for various semiconductor equipment related to wet processes, including EFEM, Sorter, and cleaning process equipment where the vertical and horizontal travel distances need to be customized according to space requirements.

Specification parameter				
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers			
Reachable Range	Arm: 1000mm	Rotation: 340°	Lifting: Customized ≥500	Track:定制
Transport Speed (average speed)	2000mm/s	200°	400~1000mm/s	800~3500mm/s
Arm Type	Quad Arms			
Repeat Precision	±0.1mm以内			
Communication Protocol	HEX/ASCII			
Communication Method	EtherNet/RS232			
Cleanliness Level	Highest ISO Class1			
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa			

FHRD-Seven-Axis Electroplating Process Manipulator

This mechanical arm is designed for material handling in cleanroom environments with corrosive liquids. It employs a closed-loop servo control system and is suitable for stable transportation.



- Optional XY Module-based Equipment Layout
- Adopting a modular dual-arm structure to achieve high-speed wafer transfer
- Adopting a modular lifting structure to achieve rapid elevation of the main body and customized design
- Can be paired with different types of Forks to meet various wafer transfer requirements under different working conditions
- Handling Weight: The arm, including the End Effector (EEF), is below 3Kg
- Wafer Fixation Methods: Vacuum Adsorption / Mechanical Clamping
- Customizable according to customer space requirements

● Application: Positioned inside the customer's electroplating process chamber to facilitate the transfer of wafers in wet processes, and the travel range of XYR can be customized according to the customer's spatial requirements.

Specification parameter				
Handling Object	12-inch Wafer			
Reachable Range (from rotation center to the third joint center)	Arm: 475mm Customizable	Theta Rotation:340°	Lifting: 500—2000mm customizable	Flip Axis: ± 180°
Handling Speed (average speed)	550mm/s	340°/s	400—1000mm/s customizable	340°/s
Arm Type	Dual Arms			
Handling Height	Depends on configuration			
Repeatability Accuracy	Within ± 0.1mm			
Communication Protocol	HEX/ASCII			
Communication Method	EtherNet/RS232			
Cleanliness	Highest ISO Class 1			
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa			

FCRS-Four-Axis Cassette Robot

This robotic arm is designed for material handling in high-cleanliness conditions, employing a closed-loop servo control system, and is suitable for high-speed transfer operations.



- Optional pseudo-horizontal multi-joint motion corresponding to parallel equipment layout
- Adopting a single-arm construction, it can achieve high-speed transfer of wafers
- Adopting a single Z-axis lifting structure, it is possible to achieve rapid lifting and lowering of the main body
- Carrying capacity: Below 4Kg at the third joint of the arm
- Capable of being paired with various types of custom forks to meet the transportation needs of different specifications of Cassette/reagent boxes
- Fixed Method: Clamping Type
- Fixed methods can be chosen either from the top or bottom based on the equipment layout

● Application: Suitable for handling open cassettes, reagent boxes, and similar items in clean environments, with customization available based on specific usage conditions.

Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch Cassette/Suitable Size Reagent Box		
Reachable Range (from rotation center to the third joint center)	Arm: 290/376mm	Theta Rotation:340°	Lifting: 300/400/500
Handling Speed (average speed)	750mm/s	235°/s	500mm/s
Arm Type	Single Arm		
Handling Height	Configuration dependent		
Repeatability Accuracy	± 0.1mm Within		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

FWRD-ZD Five-Axis Dual-Z Robot Series

This robotic arm is designed for material handling in high-cleanliness conditions, employing a closed-loop servo control system, and is suitable for high-speed transfer operations.



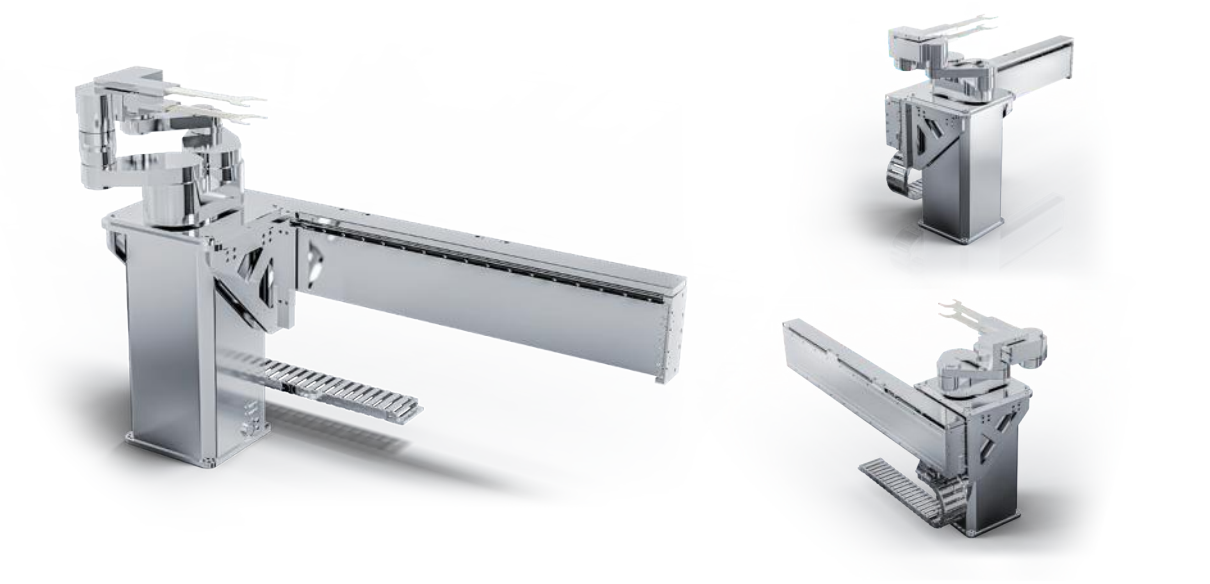
- The robot is equipped with four forks to accommodate dry/wet robotic arms
- The dual-arm configuration can achieve high-speed wafer transfer
- Using a dual Z-axis lifting structure, rapid lifting and lowering of the main body can be achieved within a high travel range.
- Carrying capacity: Below 3Kg at the third joint of the arm
- Capable of being paired with different types of Forks to meet various wafer transfer requirements
- Wafer holding methods: Vacuum suction type/Clamping type/Clamping and lifting type/Contact Bernoulli type / Non-contact Bernoulli type
- Based on the equipment layout, you can choose either an upper or lower fixing method

Specification parameter			
Handling Object	3-inch/4-inch/6-inch/8-inch/12-inch wafers		
Reachable Range	Arm: 290/376mm	Theta Rotation:340°	Lifting: 300/400/500
Handling Speed (average speed)	750mm/s	235°/s	800mm/s
Arm Type	Dual Arms		
Handling Height	820--1020mm		
Repeatability Accuracy	±0.1mm以内		
Communication Protocol	HEX/ASCII		
Communication Method	EtherNet/RS232		
Cleanliness	Highest ISO Class 1		
Facilities	Power: 220V, 10A, Vacuum: -70~-90Kpa, Positive Pressure: 0.1—0.5Mpa		

Optional TRACK Axis Series

With the optional Track axis, it can be coordinated with Fortrend Robot to be suitable for 2-4 LOADPORT wafertransfer

Side-Mounted TRACK



Floor-Mounted TRACK

